



Material Content Data Sheet



Sales Product Name		BTS244Z E3062A		Issued		24. January 2018		
MA#		MA001225870						
Package		PG-TO263-5-2		Weight*		1514.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.082	0.53	0.53	5337	5337
leadframe	non noble metal	iron	7439-89-6	0.790	0.05		521	
	inorganic material	phosphorus	7723-14-0	0.237	0.02		156	
	non noble metal	copper	7440-50-8	788.527	52.07	52.14	520716	521393
wire	non noble metal	aluminium	7429-90-5	1.825	0.12	0.12	1205	1205
encapsulation	organic material	carbon black	1333-86-4	8.813	0.58		5820	
	plastics	epoxy resin	-	96.941	6.40		64016	
	inorganic material	silicondioxide	60676-86-0	481.767	31.81	38.79	318142	387978
leadfinish	non noble metal	tin	7440-31-5	10.339	0.68	0.68	6828	6828
plating	inorganic material	phosphorus	7723-14-0	0.008	0.00		5	
	non noble metal	nickel	7440-02-0	3.422	0.23	0.23	2259	2264
glue	plastics	Polyimide	26023-21-2	0.157	0.01	0.01	103	103
solder	noble metal	silver	7440-22-4	0.133	0.01		88	
	non noble metal	tin	7440-31-5	0.107	0.01		70	
	non noble metal	lead	7439-92-1	5.088	0.34	0.36	3360	3518
heatspreader	non noble metal	iron	7439-89-6	0.108	0.01		71	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	copper	7440-50-8	107.943	7.13	7.14	71282	71374
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com